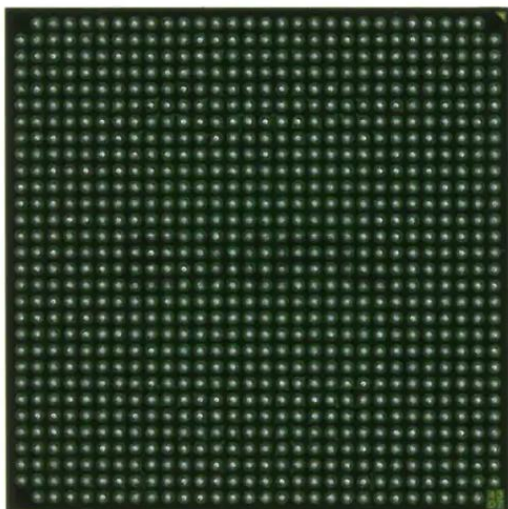




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1232
Number of Logic Elements/Cells	11088
Total RAM Bits	811008
Number of I/O	396
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp7-6ffg896c

Notice of Disclaimer

THE XILINX HARDWARE FPGA AND CPLD DEVICES REFERRED TO HEREIN ("PRODUCTS") ARE SUBJECT TO THE TERMS AND CONDITIONS OF THE XILINX LIMITED WARRANTY WHICH CAN BE VIEWED AT <http://www.xilinx.com/warranty.htm>. THIS LIMITED WARRANTY DOES NOT EXTEND TO ANY USE OF PRODUCTS IN AN APPLICATION OR ENVIRONMENT THAT IS NOT WITHIN THE SPECIFICATIONS STATED IN THE XILINX DATA SHEET. ALL SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE. PRODUCTS ARE NOT DESIGNED OR INTENDED TO BE FAIL-SAFE OR FOR USE IN ANY APPLICATION REQUIRING FAIL-SAFE PERFORMANCE, SUCH AS LIFE-SUPPORT OR SAFETY DEVICES OR SYSTEMS, OR ANY OTHER APPLICATION THAT INVOKES THE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). USE OF PRODUCTS IN CRITICAL APPLICATIONS IS AT THE SOLE RISK OF CUSTOMER, SUBJECT TO APPLICABLE LAWS AND REGULATIONS.

Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)

CRC may adjust certain trailing bytes to generate the required running disparity at the end of the packet.

On the receiver side, the CRC logic verifies the received CRC value, supporting the same standards as above.

The CRC logic also supports a user mode, with a simple data packet structure beginning and ending with user-defined SOP and EOP characters.

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, two programmable loop-back features are available.

One option, serial loopback, places the gigabit transceiver into a state where transmit data is directly fed back to the receiver. An important point to note is that the feedback path is at the output pads of the transmitter. This tests the entirety of the transmitter and receiver.

The second option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs

remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset recenters the transmission FIFO, and resets all transmitter registers and the 8B/10B decoder. The receiver reset recenters the receiver elastic buffer, and resets all receiver registers and the 8B/10B encoder. Neither reset has any effect on the PLLs.

Power

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 2.5V source, and passive filtering is not required.

Power Down

The Power Down module is controlled by the transceiver's POWERDOWN input pin. The Power Down pin on the FPGA package has no effect on the transceiver.

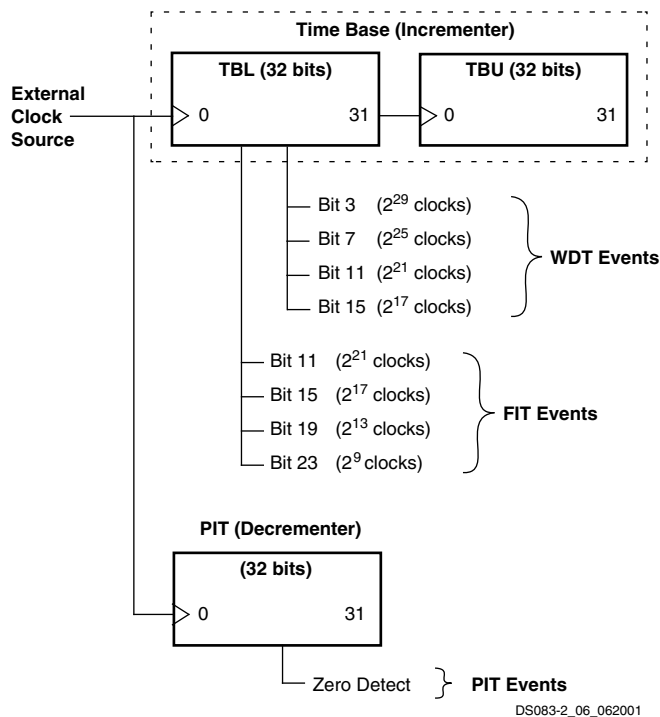


Figure 17: Relationship of Timer Facilities to Base Clock

Interrupts

The PPC405 provides an interface to an interrupt controller that is logically outside the PPC405 core. This controller combines the asynchronous interrupt inputs and presents them to the embedded core as a single interrupt signal. The sources of asynchronous interrupts are external signals, the JTAG/debug unit, and any implemented peripherals.

Debug Logic

All architected resources on the embedded PPC405 core can be accessed through the debug logic. Upon a debug event, the PPC405 core provides debug information to an external debug tool. Three different types of tools are supported depending on the debug mode: ROM monitors, JTAG debuggers, and instruction trace tools.

In internal debug mode, a debug event enables exception-handling software at a dedicated interrupt vector to take

over the CPU core and communicate with a debug tool. The debug tool has read-write access to all registers and can set hardware or software breakpoints. ROM monitors typically use the internal debug mode.

In external debug mode, the CPU core enters stop state (stops instruction execution) when a debug event occurs. This mode offers a debug tool read-write access to all registers in the PPC405 core. Once the CPU core is in stop state, the debug tool can start the CPU core, step an instruction, freeze the timers, or set hardware or software breakpoints. In addition to CPU core control, the debug logic is capable of writing instructions into the instruction cache, eliminating the need for external memory during initial board bring-up. Communication to a debug tool using external debug mode is through the JTAG port.

Debug wait mode offers the same functionality as external debug mode with one exception. In debug wait mode, the CPU core goes into wait state instead of stop state after a debug event. Wait state is identical to stop state until an interrupt occurs. In wait state, the PPC405 core can vector to an exception handler, service an interrupt and return to wait state. This mode is particularly useful when debugging real time control systems.

Real-time trace debug mode is always enabled. The debug logic continuously broadcasts instruction trace information to the trace port. When a debug event occurs, the debug logic signals an external debug tool to save instruction trace information before and after the event. The number of instructions traced depends on the trace tool.

Debug events signal the debug logic to stop the CPU core, put the CPU core in debug wait state, cause a debug exception or save instruction trace information.

Big Endian and Little Endian Support

The embedded PPC405 core supports big endian or little endian byte ordering for instructions stored in external memory. Since the PowerPC architecture is big endian internally, the ICU rearranges the instructions stored as little endian into the big endian format. Therefore, the instruction cache always contains instructions in big endian format so that the byte ordering is correct for the execution unit. This feature allows the 405 core to be used in systems designed to function in a little endian environment.

The DCM has the following general control signals:

- RST input pin: resets the entire DCM
- LOCKED output pin: asserted High when all enabled DCM circuits have locked.
- STATUS output pins (active High): shown in [Table 27](#).

Table 27: DCM Status Pins

Status Pin	Function
0	Phase Shift Overflow
1	CLKIN Stopped
2	CLKFX Stopped
3	N/A
4	N/A
5	N/A
6	N/A
7	N/A

Clock De-skew

The DCM de-skews the output clocks relative to the input clock by automatically adjusting a digital delay line. Additional delay is introduced so that clock edges arrive at internal registers and block RAMs simultaneously with the clock edges arriving at the input clock pad. Alternatively, external clocks, which are also de-skewed relative to the input clock, can be generated for board-level routing. All DCM output clocks are phase-aligned to CLK0 and, therefore, are also phase-aligned to the input clock.

To achieve clock de-skew, connect the CLKFB input to CLK0. Note that CLKFB must always be connected, unless only the CLKFX or CLKFX180 outputs are used and de-skew is not required.

Frequency Synthesis

The DCM provides flexible methods for generating new clock frequencies. Each method has a different operating frequency range and different AC characteristics. The CLK2X and CLK2X180 outputs double the clock frequency. The CLKDV output creates divided output clocks with division options of 1.5, 2, 2.5, 3, 3.5, 4, 4.5, 5, 5.5, 6, 6.5, 7, 7.5, 8, 9, 10, 11, 12, 13, 14, 15, and 16.

The CLKFX and CLKFX180 outputs can be used to produce clocks at the following frequency:

$$\text{FREQ}_{\text{CLKFX}} = (M/D) \cdot \text{FREQ}_{\text{CLKIN}}$$

where M and D are two integers. Specifications for M and D are provided under **DCM Timing Parameters** in [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics](#). By default, $M = 4$ and $D = 1$,

which results in a clock output frequency four times faster than the clock input frequency (CLKIN).

CLK2X180 is phase shifted 180 degrees relative to CLK2X. CLKFX180 is phase shifted 180 degrees relative to CLKFX. All frequency synthesis outputs automatically have 50/50 duty cycles, with the exception of the CLKDV output when performing a non-integer divide in high-frequency mode. See [Table 28](#) for more details.

Note that CLK2X and CLK2X180 are not available in high-frequency mode.

Table 28: CLKDV Duty Cycle for Non-integer Divides

CLKDV_DIVIDE	Duty Cycle
1.5	1/3
2.5	2/5
3.5	3/7
4.5	4/9
5.5	5/11
6.5	6/13
7.5	7/15

Phase Shifting

The DCM provides additional control over clock skew through either coarse or fine-grained phase shifting. The CLK0, CLK90, CLK180, and CLK270 outputs are each phase shifted by $\frac{1}{4}$ of the input clock period relative to each other, providing coarse phase control. Note that CLK90 and CLK270 are not available in high-frequency mode.

Fine-phase adjustment affects all nine DCM output clocks. When activated, the phase shift between the rising edges of CLKIN and CLKFB is a specified fraction of the input clock period.

In variable mode, the PHASE_SHIFT value can also be dynamically incremented or decremented as determined by PSINCDEC synchronously to PSCLK, when the PSEN input is active. [Figure 63](#) illustrates the effects of fine-phase shifting. For more information on DCM features, see the [Virtex-II Pro Platform FPGA User Guide](#).

[Table 29](#) lists fine-phase shifting control pins, when used in variable mode.

Table 29: Fine Phase Shifting Control Pins

Control Pin	Direction	Function
PSINCDEC	In	Increment or decrement
PSEN	In	Enable $\pm$ phase shift
PSCLK	In	Clock for phase shift
PSDONE	Out	Active when completed



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011

Product Specification

Virtex-II Pro⁽¹⁾ Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade

commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: Absolute Maximum Ratings

Symbol	Description ⁽¹⁾		Virtex-II Pro X	Virtex-II Pro	Units
V _{CCINT}	Internal supply voltage relative to GND		−0.5 to 1.6		V
V _{CCAUX}	Auxiliary supply voltage relative to GND		−0.5 to 3.0		V
V _{CCO}	Output drivers supply voltage relative to GND		−0.5 to 3.75		V
V _{BATT}	Key memory battery backup supply		−0.5 to 4.05		V
V _{REF}	Input reference voltage		−0.3 to 3.75		V
V _{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		−0.3 to 4.05 ⁽³⁾		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		−0.5 to V _{CCO} + 0.5		V
V _{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		−0.3 to 4.05 ⁽³⁾		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		−0.5 to V _{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		−0.5 to 2.0	−0.5 to 3.0	V
AVCCAUTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		−0.5 to 3.0	−0.5 to 3.0	V
V _{TRX}	Terminal receive supply voltage relative to GND		−0.5 to 3.0	−0.5 to 3.0	V
V _{TTX}	Terminal transmit supply voltage relative to GND		−0.5 to 1.6	−0.5 to 3.0	V
T _{STG}	Storage temperature (ambient)		−65 to +150		°C
T _{SOL}	Maximum soldering temperature ⁽²⁾	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T _J	Maximum junction temperature ⁽²⁾		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the [Device Packaging and Thermal Characteristics Guide](#) information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to [XAPP659](#) for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Table 3: Virtex-II Pro Available I/Os and RocketIO MGT Pins per Device/Package Combination (Continued)

Virtex-II Pro Device	User I/Os & RocketIO MGT Pins	Virtex-II Pro Package ⁽¹⁾									
		FG256/ FGG256	FG456/ FGG456	FG676/ FGG456	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
XC2VP70	Available User I/Os	-	-		-	-	-	-	964	996	-
	RocketIO MGT Pins	-	-		-	-	-	-	144	180	-
	Differential I/O Pairs	-	-		-	-	-	-	476	492	-
XC2VPX70	Available User I/Os	-	-		-	-	-	-	-	992	-
	RocketIO X MGT Pins	-	-		-	-	-	-	-	180	-
	Differential I/O Pairs	-	-		-	-	-	-	-	490	-
XC2VP100	Available User I/Os	-	-		-	-	-	-	-	1040	1164
	RocketIO MGT Pins	-	-		-	-	-	-	-	180	0
	Differential I/O Pairs	-	-		-	-	-	-	-	512	572

Notes:

1. Wire-bond packages include FGGnnn Pb-free versions. See [Virtex-II Pro Ordering Examples \(Module 1\)](#)

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L07P_1	F14			
1	IO_L06N_1	C15			
1	IO_L06P_1	D15			
1	IO_L05_1/No_Pair	E15			
1	IO_L03N_1/VREF_1	C16			
1	IO_L03P_1	D16			
1	IO_L02N_1	E16			
1	IO_L02P_1	E17			
1	IO_L01N_1/VRP_1	D17			
1	IO_L01P_1/VRN_1	D18			
2	IO_L01N_2/VRP_2	C21			
2	IO_L01P_2/VRN_2	C22			
2	IO_L02N_2	D21			
2	IO_L02P_2	D22			
2	IO_L03N_2	E19			
2	IO_L03P_2	E20			
2	IO_L04N_2/VREF_2	E21			
2	IO_L04P_2	E22			
2	IO_L06N_2	F19			
2	IO_L06P_2	F20			
2	IO_L43N_2	F21	NC		
2	IO_L43P_2	F22	NC		
2	IO_L46N_2/VREF_2	F18	NC		
2	IO_L46P_2	G18	NC		
2	IO_L48N_2	G19	NC		
2	IO_L48P_2	G20	NC		
2	IO_L49N_2	G21	NC		
2	IO_L49P_2	G22	NC		
2	IO_L50N_2	H19	NC		
2	IO_L50P_2	H20	NC		
2	IO_L52N_2/VREF_2	H21	NC		
2	IO_L52P_2	H22	NC		
2	IO_L54N_2	H18	NC		
2	IO_L54P_2	J17	NC		
2	IO_L55N_2	J19	NC		
2	IO_L55P_2	J20	NC		

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L52N_6	U22	NC		
6	IO_L53P_6	U23	NC		
6	IO_L53N_6	U24	NC		
6	IO_L54P_6	V26	NC		
6	IO_L54N_6	U26	NC		
6	IO_L55P_6	U20	NC		
6	IO_L55N_6	T19	NC		
6	IO_L56P_6	T20	NC		
6	IO_L56N_6	R20	NC		
6	IO_L57P_6	T21	NC		
6	IO_L57N_6/VREF_6	T22	NC		
6	IO_L58P_6	T23	NC		
6	IO_L58N_6	T24	NC		
6	IO_L59P_6	T25	NC		
6	IO_L59N_6	T26	NC		
6	IO_L60P_6	R19	NC		
6	IO_L60N_6	P19	NC		
6	IO_L85P_6	R21			
6	IO_L85N_6	R22			
6	IO_L86P_6	R23			
6	IO_L86N_6	R24			
6	IO_L87P_6	R25			
6	IO_L87N_6/VREF_6	R26			
6	IO_L88P_6	P20			
6	IO_L88N_6	P21			
6	IO_L89P_6	P22			
6	IO_L89N_6	P23			
6	IO_L90P_6	P24			
6	IO_L90N_6	P25			
7	IO_L90P_7	N25			
7	IO_L90N_7	N24			
7	IO_L89P_7	N23			
7	IO_L89N_7	N22			
7	IO_L88P_7	N21			
7	IO_L88N_7/VREF_7	N20			
7	IO_L87P_7	M26			

FF672 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

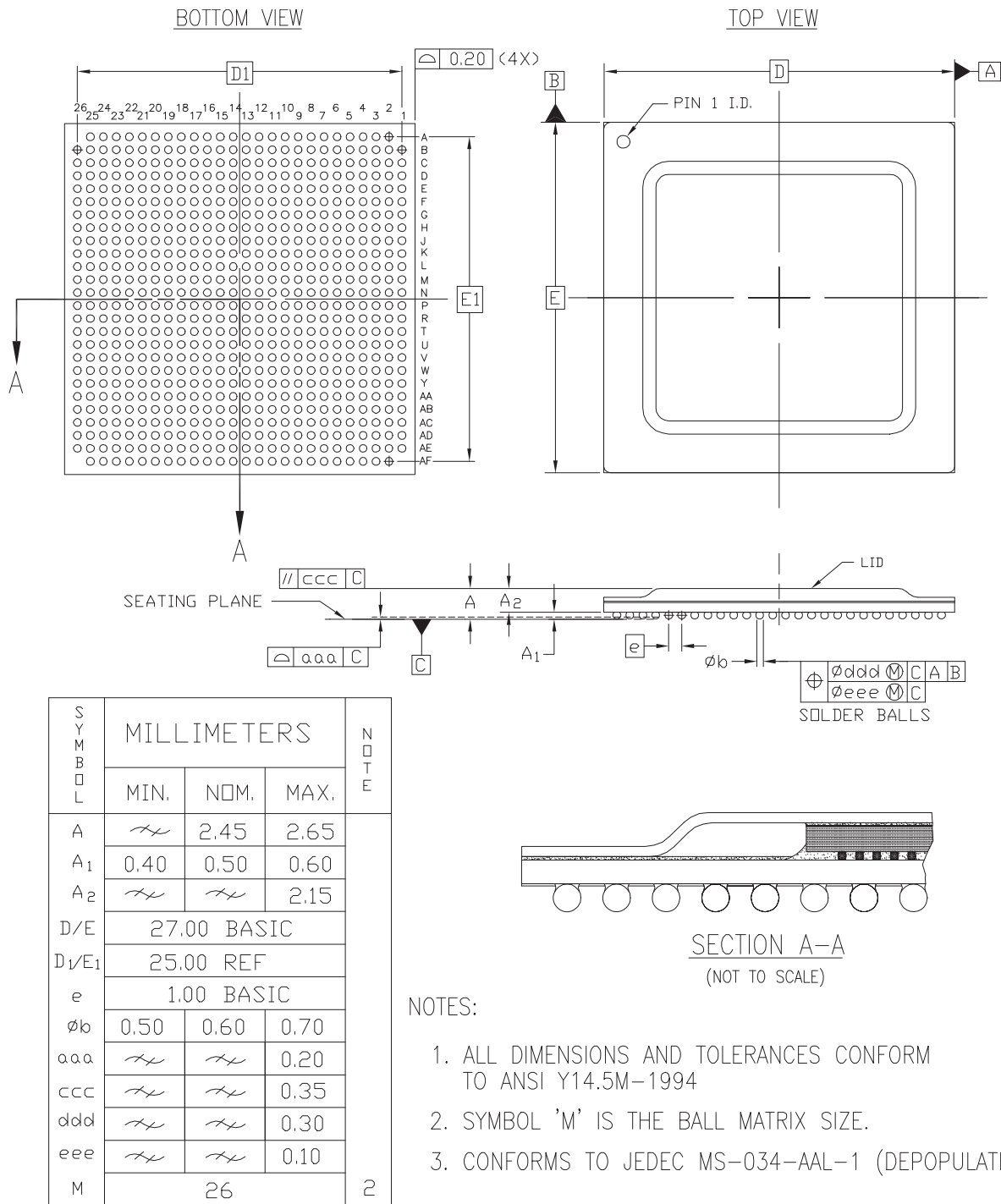


Figure 4: FF672 Flip-Chip Fine-Pitch BGA Package Specifications

FF896 Flip-Chip Fine-Pitch BGA Package

As shown in Table 9, XC2VP7, XC2VP20, and XC2VP30 Virtex-II Pro devices are available in the FF896 flip-chip fine-pitch BGA package. Pins in each of these devices are the same, except for differences shown in the "No Connects" column. Following this table are the **FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)**.

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
2	IO_L05N_2	J8				
2	IO_L05P_2	J7				
2	IO_L06N_2	F5				
2	IO_L06P_2	F4				
2	IO_L15N_2	G4	NC			
2	IO_L15P_2	G3	NC			
2	IO_L16N_2/VREF_2	G6	NC			
2	IO_L16P_2	G5	NC			
2	IO_L17N_2	F2	NC			
2	IO_L17P_2	F1	NC			
2	IO_L18N_2	L10	NC			
2	IO_L18P_2	L9	NC			
2	IO_L19N_2	H6	NC			
2	IO_L19P_2	H5	NC			
2	IO_L20N_2	G2	NC			
2	IO_L20P_2	G1	NC			
2	IO_L21N_2	J6	NC			
2	IO_L21P_2	J5	NC			
2	IO_L22N_2/VREF_2	J4	NC			
2	IO_L22P_2	J3	NC			
2	IO_L23N_2	K8	NC			
2	IO_L23P_2	K7	NC			
2	IO_L24N_2	H4	NC			
2	IO_L24P_2	H3	NC			
2	IO_L31N_2	H2				
2	IO_L31P_2	H1				
2	IO_L32N_2	M10				
2	IO_L32P_2	M9				
2	IO_L33N_2	K5				
2	IO_L33P_2	K4				
2	IO_L34N_2/VREF_2	J2				
2	IO_L34P_2	K2				
2	IO_L35N_2	L8				
2	IO_L35P_2	L7				
2	IO_L36N_2	L6				
2	IO_L36P_2	L5				
2	IO_L37N_2	K1				
2	IO_L37P_2	L1				

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L53P_6	W25				
6	IO_L53N_6	W26				
6	IO_L54P_6	AB33				
6	IO_L54N_6	AA33				
6	IO_L55P_6	Y28				
6	IO_L55N_6	Y29				
6	IO_L56P_6	W27				
6	IO_L56N_6	W28				
6	IO_L57P_6	Y31				
6	IO_L57N_6/VREF_6	Y32				
6	IO_L58P_6	W29				
6	IO_L58N_6	W30				
6	IO_L59P_6	W24				
6	IO_L59N_6	V24				
6	IO_L60P_6	AA34				
6	IO_L60N_6	Y34				
6	IO_L85P_6	W31				
6	IO_L85N_6	W32				
6	IO_L86P_6	V25				
6	IO_L86N_6	V26				
6	IO_L87P_6	Y33				
6	IO_L87N_6/VREF_6	W33				
6	IO_L88P_6	V29				
6	IO_L88N_6	V30				
6	IO_L89P_6	V27				
6	IO_L89N_6	V28				
6	IO_L90P_6	V31				
6	IO_L90N_6	V32				
7	IO_L90P_7	U32				
7	IO_L90N_7	U31				
7	IO_L89P_7	U28				
7	IO_L89N_7	U27				
7	IO_L88P_7	V33				
7	IO_L88N_7/VREF_7	U33				
7	IO_L87P_7	U30				
7	IO_L87N_7	U29				
7	IO_L86P_7	U26				

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
6	IO_L44N_6	AA28		
6	IO_L45P_6	AC31		
6	IO_L45N_6/VREF_6	AC32		
6	IO_L46P_6	AC29		
6	IO_L46N_6	AC30		
6	IO_L47P_6	AA24		
6	IO_L47N_6	AA25		
6	IO_L48P_6	AB32		
6	IO_L48N_6	AB33		
6	IO_L49P_6	AB28		
6	IO_L49N_6	AB29		
6	IO_L50P_6	AA26		
6	IO_L50N_6	Y26		
6	IO_L51P_6	AA33		
6	IO_L51N_6/VREF_6	AA34		
6	IO_L52P_6	AB31		
6	IO_L52N_6	AA31		
6	IO_L53P_6	Y24		
6	IO_L53N_6	Y25		
6	IO_L54P_6	AA29		
6	IO_L54N_6	AA30		
6	IO_L55P_6	Y33		
6	IO_L55N_6	Y34		
6	IO_L56P_6	Y28		
6	IO_L56N_6	W27		
6	IO_L57P_6	AA32		
6	IO_L57N_6/VREF_6	Y32		
6	IO_L58P_6	Y29		
6	IO_L58N_6	Y30		
6	IO_L59P_6	W24		
6	IO_L59N_6	W25		
6	IO_L60P_6	W31		
6	IO_L60N_6	W32		
6	IO_L85P_6	W28		
6	IO_L85N_6	W29		
6	IO_L86P_6	V26		
6	IO_L86N_6	V27		
6	IO_L87P_6	W33		

FF1517 Flip-Chip Fine-Pitch BGA Package

As shown in [Table 12](#), XC2VP50 and XC2VP70 Virtex-II Pro devices are available in the FF1517 flip-chip fine-pitch BGA package. Following this table are the [FF1517 Flip-Chip Fine-Pitch BGA Package Specifications \(1.00mm pitch\)](#).

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L01N_0/VRP_0	D31		
0	IO_L01P_0/VRN_0	E31		
0	IO_L02N_0	K30		
0	IO_L02P_0	J30		
0	IO_L03N_0	G30		
0	IO_L03P_0/VREF_0	H30		
0	IO_L05_0/No_Pair	K28		
0	IO_L06N_0	E30		
0	IO_L06P_0	F30		
0	IO_L07N_0	C30		
0	IO_L07P_0	D30		
0	IO_L08N_0	J29		
0	IO_L08P_0	K29		
0	IO_L09N_0	G29		
0	IO_L09P_0/VREF_0	H29		
0	IO_L19N_0	E29		
0	IO_L19P_0	F29		
0	IO_L20N_0	L28		
0	IO_L20P_0	L27		
0	IO_L21N_0	C29		
0	IO_L21P_0	D29		
0	IO_L25N_0	H28		
0	IO_L25P_0	J28		
0	IO_L26N_0	M27		
0	IO_L26P_0	M26		
0	IO_L27N_0	D28		
0	IO_L27P_0/VREF_0	E28		
0	IO_L28N_0	H27	NC	
0	IO_L28P_0	J27	NC	
0	IO_L29N_0	J26	NC	
0	IO_L29P_0	K26	NC	
0	IO_L30N_0	F28	NC	
0	IO_L30P_0	G27	NC	
0	IO_L34N_0	D27	NC	

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L59P_0	N21		
0	IO_L60N_0	E23		
0	IO_L60P_0	F22		
0	IO_L64N_0	D22		
0	IO_L64P_0	E22		
0	IO_L65N_0	H21		
0	IO_L65P_0	H20		
0	IO_L66N_0	G22		
0	IO_L66P_0/VREF_0	G21		
0	IO_L67N_0	D21		
0	IO_L67P_0	E21		
0	IO_L68N_0	J21		
0	IO_L68P_0	K21		
0	IO_L69N_0	C22		
0	IO_L69P_0/VREF_0	C21		
0	IO_L73N_0	F21		
0	IO_L73P_0	F20		
0	IO_L74N_0/GCLK7P	L21		
0	IO_L74P_0/GCLK6S	M21		
0	IO_L75N_0/GCLK5P	D20		
0	IO_L75P_0/GCLK4S	E20		
1	IO_L75N_1/GCLK3P	K20		
1	IO_L75P_1/GCLK2S	J20		
1	IO_L74N_1/GCLK1P	N20		
1	IO_L74P_1/GCLK0S	M20		
1	IO_L73N_1	E19		
1	IO_L73P_1	D19		
1	IO_L69N_1/VREF_1	G19		
1	IO_L69P_1	F19		
1	IO_L68N_1	L19		
1	IO_L68P_1	K19		
1	IO_L67N_1	J19		
1	IO_L67P_1	H19		
1	IO_L66N_1/VREF_1	C19		
1	IO_L66P_1	C18		
1	IO_L65N_1	N19		
1	IO_L65P_1	M19		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L26P_2		N12		
2	IO_L27N_2		P9		
2	IO_L27P_2		P10		
2	IO_L28N_2/VREF_2		P7		
2	IO_L28P_2		P8		
2	IO_L29N_2		P11		
2	IO_L29P_2		P12		
2	IO_L30N_2		P5		
2	IO_L30P_2		P6		
2	IO_L31N_2		P1		
2	IO_L31P_2		P2		
2	IO_L32N_2		R9		
2	IO_L32P_2		R10		
2	IO_L33N_2		R5		
2	IO_L33P_2		R6		
2	IO_L34N_2/VREF_2		P3		
2	IO_L34P_2		R3		
2	IO_L35N_2		R1		
2	IO_L35P_2		R2		
2	IO_L36N_2		R11		
2	IO_L36P_2		R12		
2	IO_L37N_2		T6		
2	IO_L37P_2		T7		
2	IO_L38N_2		T8		
2	IO_L38P_2		R8		
2	IO_L39N_2		T4		
2	IO_L39P_2		T5		
2	IO_L40N_2/VREF_2		T2		
2	IO_L40P_2		T3		
2	IO_L41N_2		T10		
2	IO_L41P_2		T11		
2	IO_L42N_2		U7		
2	IO_L42P_2		U8		
2	IO_L43N_2		U5		
2	IO_L43P_2		U6		
2	IO_L44N_2		U9		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L60P_4		AR19		
4	IO_L64N_4		AV19		
4	IO_L64P_4		AU19		
4	IO_L65N_4		AW19		
4	IO_L65P_4		AY19		
4	IO_L66N_4		AL21		
4	IO_L66P_4/VREF_4		AL20		
4	IO_L67N_4		AN20		
4	IO_L67P_4		AM20		
4	IO_L68N_4		AP20		
4	IO_L68P_4		AR20		
4	IO_L69N_4		AV20		
4	IO_L69P_4/VREF_4		AU20		
4	IO_L73N_4		AY20		
4	IO_L73P_4		AW20		
4	IO_L74N_4/GCLK3S		AN21		
4	IO_L74P_4/GCLK2P		AP21		
4	IO_L75N_4/GCLK1S		AU21		
4	IO_L75P_4/GCLK0P		AT21		
5	IO_L75N_5/GCLK7S	BREFCLKN	AT22		
5	IO_L75P_5/GCLK6P	BREFCLKP	AU22		
5	IO_L74N_5/GCLK5S		AP22		
5	IO_L74P_5/GCLK4P		AN22		
5	IO_L73N_5		AW23		
5	IO_L73P_5		AY23		
5	IO_L69N_5/VREF_5		AU23		
5	IO_L69P_5		AV23		
5	IO_L68N_5		AR23		
5	IO_L68P_5		AP23		
5	IO_L67N_5		AM23		
5	IO_L67P_5		AN23		
5	IO_L66N_5/VREF_5		AL23		
5	IO_L66P_5		AL22		
5	IO_L65N_5		AY24		
5	IO_L65P_5		AW24		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCINT		U26		
N/A	VCCINT		U17		
N/A	VCCINT		U16		
N/A	VCCINT		T27		
N/A	VCCINT		T26		
N/A	VCCINT		T25		
N/A	VCCINT		T24		
N/A	VCCINT		T23		
N/A	VCCINT		T22		
N/A	VCCINT		T21		
N/A	VCCINT		T20		
N/A	VCCINT		T19		
N/A	VCCINT		T18		
N/A	VCCINT		T17		
N/A	VCCINT		T16		
N/A	VCCINT		R28		
N/A	VCCINT		R27		
N/A	VCCINT		R26		
N/A	VCCINT		R17		
N/A	VCCINT		R16		
N/A	VCCINT		R15		
N/A	VCCINT		P29		
N/A	VCCINT		P28		
N/A	VCCINT		P27		
N/A	VCCINT		P16		
N/A	VCCINT		P15		
N/A	VCCINT		P14		
N/A	VCCINT		N30		
N/A	VCCINT		N13		
N/A	VCCAUX		AB42		
N/A	VCCAUX		AB41		
N/A	VCCAUX		AB2		
N/A	VCCAUX		AB1		
N/A	VCCAUX		AC42		
N/A	VCCAUX		AC1		
N/A	VCCAUX		AM32		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L58P_4	AW19	
4	IO_L59N_4	AP19	
4	IO_L59P_4	AN19	
4	IO_L60N_4	BB19	
4	IO_L60P_4	BA19	
4	IO_L64N_4	AU20	
4	IO_L64P_4	AT20	
4	IO_L65N_4	AL21	
4	IO_L65P_4	AL20	
4	IO_L66N_4	BA20	
4	IO_L66P_4/VREF_4	AY20	
4	IO_L67N_4	AR21	
4	IO_L67P_4	AP21	
4	IO_L68N_4	AN20	
4	IO_L68P_4	AM20	
4	IO_L69N_4	AU21	
4	IO_L69P_4/VREF_4	AT21	
4	IO_L73N_4	AW21	
4	IO_L73P_4	AV21	
4	IO_L74N_4/GCLK3S	AN21	
4	IO_L74P_4/GCLK2P	AM21	
4	IO_L75N_4/GCLK1S	BA21	
4	IO_L75P_4/GCLK0P	AY21	
5	IO_L75N_5/GCLK7S	AY22	
5	IO_L75P_5/GCLK6P	BA22	
5	IO_L74N_5/GCLK5S	AM22	
5	IO_L74P_5/GCLK4P	AN22	
5	IO_L73N_5	AV22	
5	IO_L73P_5	AW22	
5	IO_L69N_5/VREF_5	AT22	
5	IO_L69P_5	AU22	
5	IO_L68N_5	AM23	
5	IO_L68P_5	AN23	
5	IO_L67N_5	AP22	
5	IO_L67P_5	AR22	
5	IO_L66N_5/VREF_5	AY23	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L79P_7	D41	
7	IO_L79N_7	D42	
7	IO_L78P_7	C39	
7	IO_L78N_7	C40	
7	IO_L77P_7	H34	
7	IO_L77N_7	H35	
7	IO_L76P_7	C37	
7	IO_L76N_7/VREF_7	D36	
7	IO_L75P_7	B38	
7	IO_L75N_7	C38	
7	IO_L74P_7	F34	
7	IO_L74N_7	G34	
7	IO_L73P_7	C35	
7	IO_L73N_7	C36	
7	IO_L06P_7	A39	
7	IO_L06N_7	B39	
7	IO_L05P_7	D34	
7	IO_L05N_7	D35	
7	IO_L04P_7	A37	
7	IO_L04N_7/VREF_7	B37	
7	IO_L03P_7	A36	
7	IO_L03N_7	B36	
7	IO_L02P_7	B34	
7	IO_L02N_7	C34	
7	IO_L01P_7/VRN_7	A35	
7	IO_L01N_7/VRP_7	B35	
7	VCCO_7	W39	
7	VCCO_7	P39	
7	VCCO_7	K39	
7	VCCO_7	F39	
7	VCCO_7	D37	
7	VCCO_7	W35	
7	VCCO_7	P35	
7	VCCO_7	K35	
7	VCCO_7	M33	
7	VCCO_7	H33	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	GND	E13	
N/A	GND	A13	
N/A	GND	AD12	
N/A	GND	W12	
N/A	GND	BB9	
N/A	GND	AV9	
N/A	GND	AP9	
N/A	GND	AK9	
N/A	GND	AF9	
N/A	GND	AC9	
N/A	GND	Y9	
N/A	GND	U9	
N/A	GND	N9	
N/A	GND	J9	
N/A	GND	E9	
N/A	GND	A9	
N/A	GND	BB5	
N/A	GND	AV5	
N/A	GND	AP5	
N/A	GND	AK5	
N/A	GND	AF5	
N/A	GND	AC5	
N/A	GND	Y5	
N/A	GND	U5	
N/A	GND	N5	
N/A	GND	J5	
N/A	GND	E5	
N/A	GND	A5	
N/A	GND	BA3	
N/A	GND	B3	
N/A	GND	BA2	
N/A	GND	AY2	
N/A	GND	C2	
N/A	GND	B2	
N/A	GND	AV1	
N/A	GND	AP1	
N/A	GND	AK1	